

ABSTRACT

Provided is a photosensitive adhesive composition comprising (A) an alkali-soluble polyimide having particular structural unit(s) and having a particular structure at at least one end of the main chain, (B) a glycidylamine type epoxy
5 compound of a particular structure, (C) a photopolymerizable compound, and (D) a photoinitiator, wherein (A) the alkali-soluble polyimide has a glass transition temperature of 160°C or higher. The photosensitive adhesive composition of the present invention has the ability to form patterns with an alkaline developer, excellent thermocompressibility at a low temperature to an irregular substrate after
10 exposure, and a high adhesive strength even at a high temperature.